

**In the Claims** (37 CFR §1.121(c)):

Please cancel claims 3-18 without prejudice to further prosecution of these claims in one or more continuing applications.

Please add new claims 19-35 as set forth in the following pages.

19. [NEW] The process of claim 2 further comprising the step of attaching an electrical component to the first or second conducting layer by means of a conductive polymer adhesive.
20. [NEW] The process of claim 1 wherein the substrate is formed from a polymer into a flexible sheet.
21. [NEW] The process of claim 1 wherein the substrate is coated with a copolymer adhesive.
22. [NEW] The process of claim 1 wherein the ink comprises a particulate material suspended in a mixture of a resin and an organic solvent.
23. [NEW] The process of claim 22 wherein the particulate material is a metal or carbon.
24. [NEW] The process of claim 22 wherein the resin is a polymer having amide groups.
25. [NEW] The process of claim 1 wherein the thickness of the seeding layer is from 3 to 5 microns.
26. [NEW] The process of claim 1 wherein the thickness of the first electrically conducting layer is less than or equal to 4 microns.
27. [NEW] The process of claim 1 wherein the thickness of the first electrically conducting layer is about 0.25 microns.

28. [NEW] The process of claim 1 wherein the first electrically conducting layer is formed from at least one of copper, palladium, silver, gold, platinum, and nickel.

29. [NEW] The process of claim 1 further comprising the step of soldering an electrical component on the substrate.

30. **[NEW]** The process of claim 1 further comprising the step of attaching an electrical component to the first conducting layer by means of a conductive polymer adhesive.

31. **[NEW]** An electrical assembly comprising a substrate having at least one electrically conducting layer, which layer has been formed by the process of claim 1.

32. **[NEW]** An interconnect for a battery, the interconnect being formed by the process of claim 1.

33. ~~[NEW]~~ A battery containing the interconnect of claim 32.

34. **[NEW]** A lithographic ink for use in a lithographic printing process onto a polymer substrate, the ink comprising a particulate material suspended in a mixture of a resin and an organic solvent, wherein the resin comprises a polyamide.

35. [NEW] An ink as claimed in claim 34 wherein the particulate material is a metal or carbon.